

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) An MIS-type field-effect transistor characterized in comprising:
 - a base layer;
 - a strained active semiconductor layer formed on said base layer;
 - a gate insulating film formed on said active semiconductor layer;
 - a gate electrode formed on said gate insulating film; and
 - a source/drain region formed in portions on both sides of said gate electrode inside said active semiconductor layer; wherein
 - an interface between said base layer and said active semiconductor layer is at a depth of $2T_p$ or less from the surface, where T_p is the depth of maximum concentration of an impurity introduced for forming said source/drain region.
2. (Original) An MIS-type field-effect transistor characterized in comprising:
 - a base layer;
 - a strained active semiconductor layer formed on said base layer;
 - a gate insulating film formed on said active semiconductor layer;
 - a gate electrode formed on said gate insulating film;
 - a source/drain region formed in portions on both sides of said gate electrode inside said active semiconductor layer; and
 - a gate side wall formed on the lateral face of said gate electrode; wherein
 - a portion under said gate side wall and said gate electrode of said active semiconductor layer has a greater film thickness than any other portion; and
 - an interface between said base layer and said active semiconductor layer is at a depth of $2T_p$ or less from the surface of a region disposed other than under said gate side wall and said gate electrode of said active semiconductor layer, where T_p is the depth of maximum concentration of an impurity introduced for forming said source/drain region.
 - 3. (Original) An MIS-type field-effect transistor characterized in comprising:
 - a base layer;

a strained active semiconductor layer formed on said base layer;
a gate insulating film formed on said active semiconductor layer;
a gate electrode formed on said gate insulating layer; and
a built-up layer provided with a source/drain region and formed on said active semiconductor layer on both sides of said gate electrode; wherein
said built-up layer has a film thickness of $3T_p$ or greater, where T_p is the depth of maximum concentration of an impurity introduced for forming said source/drain region.

4. (Original) The MIS-type field-effect transistor according to claim 3, characterized in that the film thickness of said built-up layer is $5T_p$.

5. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 4~~ claim 1, characterized in that said base layer is a semiconductor layer having the composition $Si_{1-x-y}Ge_xC_y$ (wherein $0 \leq x \leq 1$, $0 \leq y \leq 1$, and $0 < x + y \leq 1$).

6. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 4~~ claim 1, characterized in that said base layer is an Si layer.

7. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 6~~ claim 1, characterized in that said base layer is a semiconductor layer, and an insulator layer is formed underneath said base layer.

8. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 4~~ claim 1, characterized in that said base layer is an insulator layer.

9. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 8~~ claim 1, characterized in that said active semiconductor layer is a group IV semiconductor layer.

10. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 5, 7, and 8~~ claim 1, characterized in that said active semiconductor layer is an Si layer.

11. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 8~~ claim 1, characterized in that said active semiconductor layer is a semiconductor layer having the composition $\text{Si}_{1-x-y}\text{Ge}_x\text{C}_y$ (wherein $0 \leq x \leq 1$, $0 \leq y \leq 1$, and $0 < x + y \leq 1$).

12. (Original) The MIS-type field-effect transistor according to claim 11, characterized in comprising an Si layer with a film thickness of 10 nm or less between said active semiconductor layer and said gate insulating film.

13. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 12~~ claim 1, characterized having a gate length of 0.4 μm or less.

14. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 13~~ claim 1, characterized in that said source/drain region is formed by an ion implantation method.

15. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 13~~ claim 1, characterized in that said source/drain region is formed by a plasma doping method.

16. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 13~~ claim 1, characterized in that said source/drain region is formed by a gas-phase doping method.

17. (Currently Amended) The MIS-type field-effect transistor according to ~~any of claims 1 through 16~~ claim 1, characterized in that a portion of said source/drain region near the gate electrode is a region of low impurity concentration.